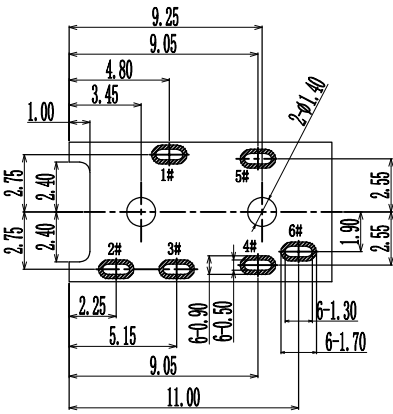
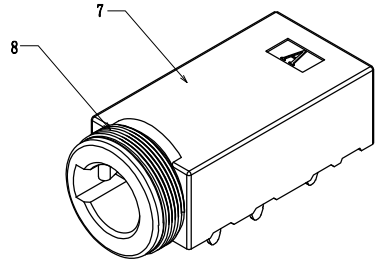
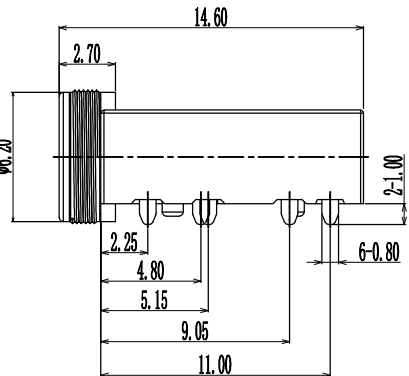
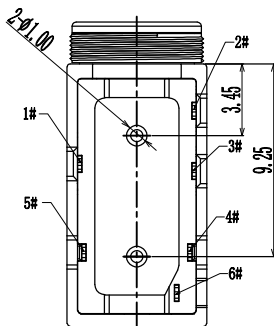
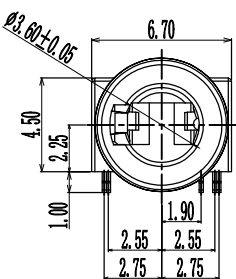
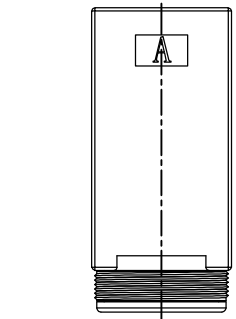


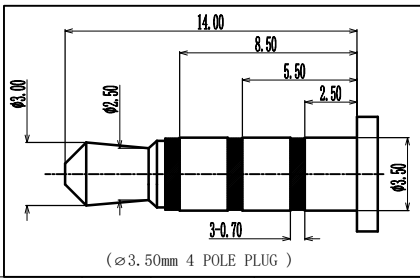
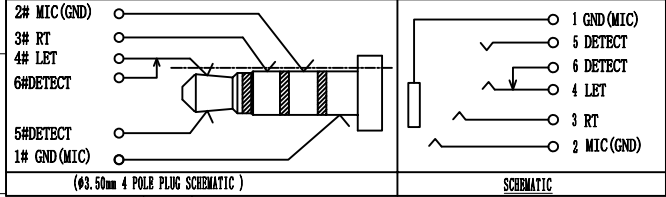


P.C.B LAYOUT T=1.00mm
TOP VIEW



3D VIEW

- 1. CONTACT CURRENT RATING: 1A.
- 2. CONTACT RESISTANCE: 100 mΩ MAX. ;
- 3. INSULATION RESISTANCE: 100MΩ MIN. ;
- 4. DIELECTRIC WITHSTANDING: 500V AC MIN. ;
- 5. DURABILITY: 5,000 CYCLES MIN. ;
- 6. CONNECTOR MATING FORCES: 30N MAX. ;
- 7. CONNECTOR UNMATING FORCES: 3N MIN. ;
- 8. TERPROOF LEVEL: IP67;



8	WATERPROOF RING	SILICA GEL	
7	HOUSING	HIGH TEMPERATURE PLASTIC MATERIALE; COLOR BLACK	
6	TERMINAL 6#	COPPER ALLOY; NICKEL UNDER PLATING OVERALL;GOLD FLASH PLATING ON SOLDER AREA ;GOLD FLASH PLATING ON CONTACT AREA	T=0.20mm
5	TERMINAL 5#	COPPER ALLOY; NICKEL UNDER PLATING OVERALL;GOLD FLASH PLATING ON SOLDER AREA ;GOLD FLASH PLATING ON CONTACT AREA	T=0.20mm
4	TERMINAL 4#	COPPER ALLOY; NICKEL UNDER PLATING OVERALL;GOLD FLASH PLATING ON SOLDER AREA ;GOLD FLASH PLATING ON CONTACT AREA	T=0.20mm
3	TERMINAL 3#	COPPER ALLOY; NICKEL UNDER PLATING OVERALL;GOLD FLASH PLATING ON SOLDER AREA ;GOLD FLASH PLATING ON CONTACT AREA	T=0.20mm
2	TERMINAL 2#	COPPER ALLOY; NICKEL UNDER PLATING OVERALL;GOLD FLASH PLATING ON SOLDER AREA ;GOLD FLASH PLATING ON CONTACT AREA	T=0.20mm
1	TERMINAL 1#	COPPER ALLOY; NICKEL UNDER PLATING OVERALL;GOLD FLASH PLATING ON SOLDER AREA ;GOLD FLASH PLATING ON CONTACT AREA	T=0.20mm
NO.	DESCRIPTION	MATERIAL	QTY

UNLESS OTHERWISE,
GENERAL TOLERANCE:
X. xxx ±0.10
X. xx ±0.20
X. x ±0.30
X. ±0.50
ANGULAR:
X. xx ±1°
X. x ±3°
X. ±5°



东莞市溪榜电子有限公司
DONG GUAN XI BANG ELECTRONICS CO., LTD.

TITLE: ϕ 3.5 WATERPROOF PHONE JACK CONNECTOR
客户图

P/N: XB-J358FR06GB001
MODEL: _____
DRAW NO.: _____

THIRD ANGLE PROJECTION


UNIT: mm

SCALE: 1:1

SIZE: A4

SHEET: 1/1

N/A	A	NEW DRAWING	2019.10.06	ZB
ECN NO.	REV.	DESCRIPTION	DATE	CHANGE